



Welcome to [E-XFL.COM](#)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	S12Z
Core Size	16-Bit
Speed	32MHz
Connectivity	CANbus, I ² C, IrDA, LINbus, SCI, SPI, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	34
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	5.5V ~ 18V
Data Converters	A/D 10x10b; D/A 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s912zvla64f0mlf

10.6.2 Analog Sub-Block	330
10.6.3 Digital Sub-Block	331
10.7 Resets	344
10.8 Interrupts	344
10.8.1 ADC Conversion Interrupt	344
10.8.2 ADC Sequence Abort Done Interrupt	344
10.8.3 ADC Error and Conversion Flow Control Issue Interrupt	345
10.9 Use Cases and Application Information	346
10.9.1 List Usage — CSL single buffer mode and RVL single buffer mode	346
10.9.2 List Usage — CSL single buffer mode and RVL double buffer mode	346
10.9.3 List Usage — CSL double buffer mode and RVL double buffer mode	347
10.9.4 List Usage — CSL double buffer mode and RVL single buffer mode	347
10.9.5 List Usage — CSL double buffer mode and RVL double buffer mode	348
10.9.6 RVL swapping in RVL double buffer mode and related registers ADCIMDRI and ADCEOLRI 348	
10.9.7 Conversion flow control application information	350
10.9.8 Continuous Conversion	352
10.9.9 Triggered Conversion — Single CSL	353
10.9.10 Fully Timing Controlled Conversion	354

Chapter 11

Digital Analog Converter (DAC_8B5V_V2)

11.1 Revision History	355
11.2 Introduction	355
11.2.1 Features	356
11.2.2 Modes of Operation	356
11.2.3 Block Diagram	357
11.3 External Signal Description	357
11.3.1 DACU Output Pin	357
11.3.2 AMP Output Pin	357
11.3.3 AMPP Input Pin	357
11.3.4 AMPM Input Pin	358
11.4 Memory Map and Register Definition	358
11.4.1 Register Summary	358
11.4.2 Register Descriptions	358
11.5 Functional Description	361
11.5.1 Functional Overview	361
11.5.2 Mode “Off”	362
11.5.3 Mode “Operational Amplifier”	362
11.5.4 Mode “Internal DAC only”	362
11.5.5 Mode “Unbuffered DAC”	362
11.5.6 Mode “Unbuffered DAC with Operational Amplifier”	362
11.5.7 Mode “Buffered DAC”	363
11.5.8 Analog output voltage calculation	363

2.3.2.8 Reserved Register



Figure 2-9. Reserved Register

¹ Read: Anytime
Write: Only in special mode.

NOTE

This reserved register is designed for factory test purposes only and is not intended for general user access. Writing to this register when in special modes can alter the modules functionality.

2.3.2.9 Reserved Register

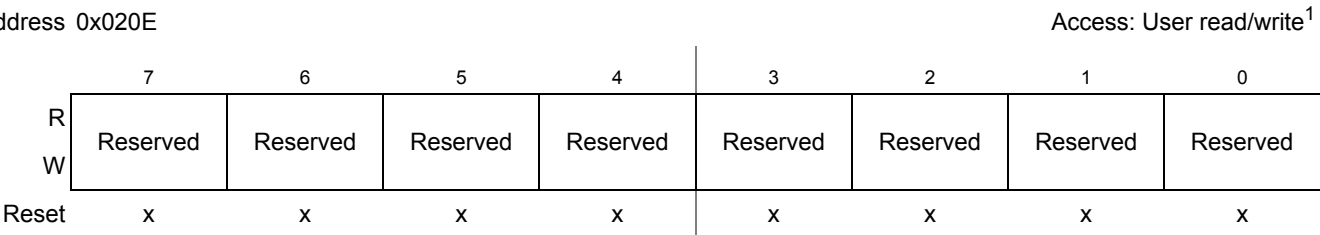


Figure 2-10. Reserved Register

¹ Read: Anytime
Write: Only in special mode

NOTE

This reserved register is designed for factory test purposes only and is not intended for general user access. Writing to this register when in special modes can alter the modules functionality.

2.3.4.7 Port L Input Divider Ratio Selection Register (PIRL)

Address 0x033E

Access: User read/write¹

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	PIRL0[1:0]	
W								
Reset	0	0	0	0	0	0	0	0

Figure 2-29. Port L Input Divider Ratio Selection Register (PIRL)

¹ Read: Anytime
Write: Anytime

Table 2-26. PIRL Register Field Descriptions

Field	Description
1–0 PIRL0	Port L Input Divider Ratio Select — These bits select one of three voltage divider ratios for the associated high-voltage input pin in analog mode. 1x Ratio _{12_HVI} selected 01 Ratio _{L_HVI} selected 00 Ratio _{H_HVI} selected

2.4 Functional Description

2.4.1 General

Each pin except BKGD can act as general-purpose I/O. In addition each pin can act as an output or input of a peripheral module.

2.4.2 Registers

Table 2-27 lists the implemented configuration bits which are available on each port. These registers except the pin input registers can be written at any time, however a specific configuration might not become active. For example a pull-up device does not become active while the port is used as a push-pull output.

Unimplemented bits read zero.

Table 2-27. Bit Indices of Implemented Register Bits per Port

	Port Data Register	Port Input Register	Data Direction Register	Pull Device Enable Register	Polarity Select Register	Port Interrupt Enable Register	Port Interrupt Flag Register	Digital Input Enable Register	Reduced Drive Register	Wired-Or Mode Register
Port	PT	PTI	DDR	PER	PPS	PIE	PIF	DIE	RDR	WOM
E	1-0	1-0	1-0	1-0	1-0	-	-	-	-	-
ADH	1-0	1-0	1-0	1-0	1-0	1-0	1-0	1-0	-	-
ADL	7-0	7-0	7-0	7-0	7-0	7-0	7-0	7-0	-	-
T	7-0	7-0	7-0	7-0	7-0	-	-	-	-	-
S	3-0	3-0	3-0	3-0	3-0	3-0	3-0	-	-	3-0
P	7-0	7-0	7-0	7-0	7-0	7-0	7-0	-	7,5,3,1	-
J	1-0	1-0	1-0	1-0	1-0	-	-	-	-	1-0
L	-	0	-	-	0	0	0	0	-	-

2.4.3 Pin I/O Control

Figure 2-30 illustrates the data paths to and from an I/O pin. Input and output data can always be read via the input register (PTIx, [Section 2.3.3.2, “Port Input Register”](#)) independent if the pin is used as general-purpose I/O or with a shared peripheral function. If the pin is configured as input (DDRx=0, [Section 2.3.3.3, “Data Direction Register”](#)), the pin state can also be read through the data register (PTx, [Section 2.3.3.1, “Port Data Register”](#)).

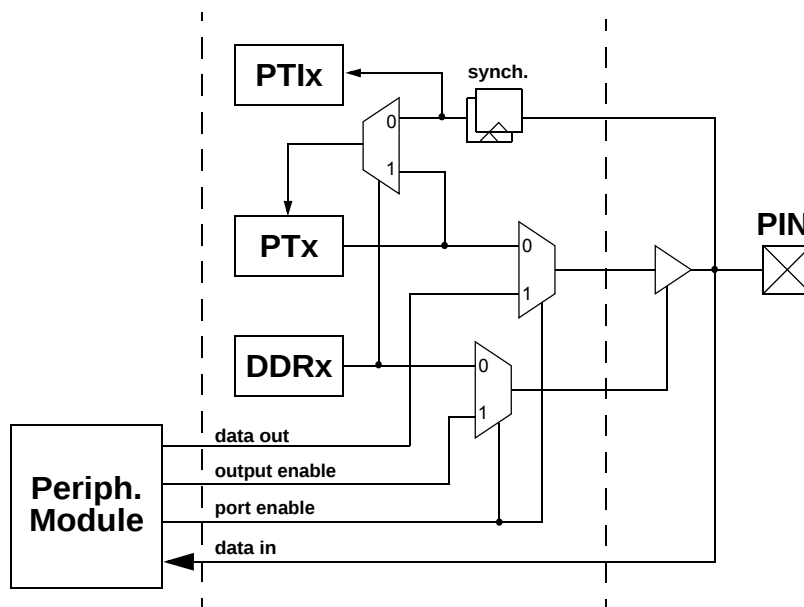


Figure 2-30. Illustration of I/O pin functionality

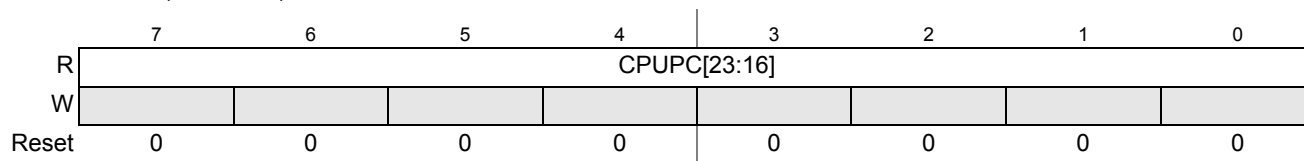
The general-purpose data direction configuration can be overruled by an enabled peripheral function shared on the same pin ([Table 2-28](#)). If more than one peripheral function is available and enabled at the

Table 4-6. MMCCCRH and MMCCCRH Field Descriptions

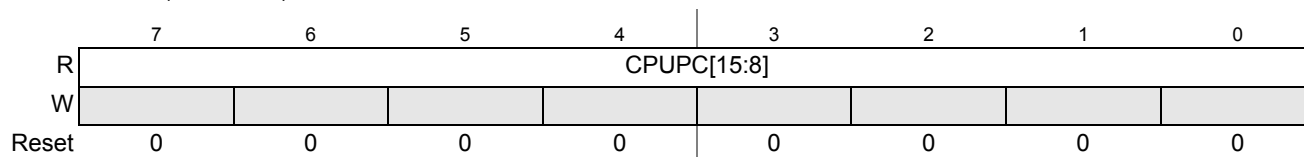
Field	Description
7 (MMCCCRH) CPUU	S12ZCPU User State Flag — This bit shows the state of the user/supervisor mode bit in the S12ZCPU's CCR at the time the access violation has occurred. The S12ZCPU user state flag is read-only; it will be automatically updated when the next error condition is flagged through the MMCEC register. This bit is undefined if the error code registers (MMCECn) are cleared.
6 (MMCCCRH) CPUX	S12ZCPU X-Interrupt Mask — This bit shows the state of the X-interrupt mask in the S12ZCPU's CCR at the time the access violation has occurred. The S12ZCPU X-interrupt mask is read-only; it will be automatically updated when the next error condition is flagged through the MMCEC register. This bit is undefined if the error code registers (MMCECn) are cleared.
4 (MMCCCRH) CPUI	S12ZCPU I-Interrupt Mask — This bit shows the state of the I-interrupt mask in the CPU's CCR at the time the access violation has occurred. The S12ZCPU I-interrupt mask is read-only; it will be automatically updated when the next error condition is flagged through the MMCEC register. This bit is undefined if the error code registers (MMCECn) are cleared.

4.3.2.4 Captured S12ZCPU Program Counter (MMCPCH, MMPCPM, MMCPCL)

Address: 0x0085 (MMCPCH)



Address: 0x0086 (MMPCPM)



Address: 0x0087 (MMCPCL)

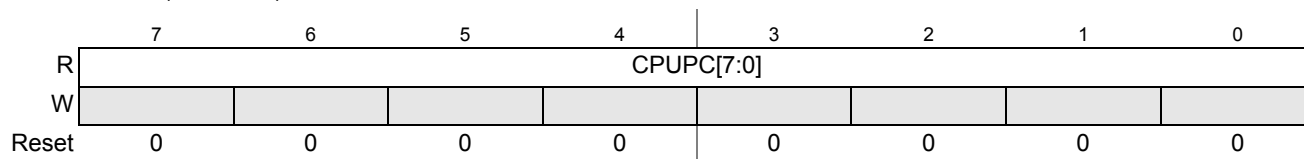


Figure 4-7. Captured S12ZCPU Program Counter (MMCPCH, MMPCPM, MMCPCL)

Read: Anytime

Write: Never

If the ACK pulse handshake protocol is enabled and STEAL is cleared, then the BDC waits for the first free bus cycle to make a non-intrusive access. If no free bus cycle occurs within 512 core clock cycles then the BDC aborts the access, sets the NORESP bit and uses a long ACK pulse to indicate an error condition to the host.

Table 5-8 summarizes the BDC command set. The subsequent sections describe each command in detail and illustrate the command structure in a series of packets, each consisting of eight bit times starting with a falling edge. The bar across the top of the blocks indicates that the BKGD line idles in the high state. The time for an 8-bit command is 8×16 target BDCSI clock cycles.

The nomenclature below is used to describe the structure of the BDC commands. Commands begin with an 8-bit hexadecimal command code in the host-to-target direction (most significant bit first)

/	=	separates parts of the command
d	=	delay 16 target BDCSI clock cycles (DLY)
dack	=	delay (16 cycles) no ACK; or delay ($\Rightarrow$ 32 cycles) then ACK.(DACK)
ad24	=	24-bit memory address in the host-to-target direction
rd8	=	8 bits of read data in the target-to-host direction
rd16	=	16 bits of read data in the target-to-host direction
rd24	=	24 bits of read data in the target-to-host direction
rd32	=	32 bits of read data in the target-to-host direction
rd64	=	64 bits of read data in the target-to-host direction
rd.sz	=	read data, size defined by sz, in the target-to-host direction
wd8	=	8 bits of write data in the host-to-target direction
wd16	=	16 bits of write data in the host-to-target direction
wd32	=	32 bits of write data in the host-to-target direction
wd.sz	=	write data, size defined by sz, in the host-to-target direction
ss	=	the contents of BDCCSR in the target-to-host direction
sz	=	memory operand size (00 = byte, 01 = word, 10 = long) (sz = 11 is reserved and currently defaults to long)
crn	=	core register number, 32-bit data width
WS	=	command suffix signaling the operation is with status

Table 5-8. BDC Command Summary

Command Mnemonic	Command Classification	ACK	Command Structure	Description
SYNC	Always Available	N/A	N/A ¹	Request a timed reference pulse to determine the target BDC communication speed
ACK_DISABLE	Always Available	No	0x03/d	Disable the communication handshake. This command does not issue an ACK pulse.
ACK_ENABLE	Always Available	Yes	0x02/dack	Enable the communication handshake. Issues an ACK pulse after the command is executed.
BACKGROUND	Non-Intrusive	Yes	0x04/dack	Halt the CPU if ENBDC is set. Otherwise, ignore as illegal command.

Table 9-7. CPMUCLKS Descriptions

Field	Description
7 PLLSEL	PLL Select Bit This bit selects the PLLCLK as source of the System Clocks (Core Clock and Bus Clock). PLLSEL can only be set to 0, if UPOSC=1. UPOSC= 0 sets the PLLSEL bit. Entering Full Stop Mode sets the PLLSEL bit. 0 System clocks are derived from OSCCLK if oscillator is up (UPOSC=1, $f_{bus} = f_{osc} / 2$). 1 System clocks are derived from PLLCLK, $f_{bus} = f_{PLL} / 2$.
6 PSTP	Pseudo Stop Bit This bit controls the functionality of the oscillator during Stop Mode. 0 Oscillator is disabled in Stop Mode (Full Stop Mode). 1 Oscillator continues to run in Stop Mode (Pseudo Stop Mode), option to run RTI and COP. Note: Pseudo Stop Mode allows for faster STOP recovery and reduces the mechanical stress and aging of the resonator in case of frequent STOP conditions at the expense of a slightly increased power consumption. Note: When starting up the external oscillator (either by programming OSCE bit to 1 or on exit from Full Stop Mode with OSCE bit already 1) the software must wait for a minimum time equivalent to the startup-time of the external oscillator t_{UPOSC} before entering Pseudo Stop Mode.
5 CSAD	COP in Stop Mode ACLK Disable — If this bit is set the ACLK for the COP in Stop Mode is disabled. Hence the COP is static while in Stop Mode and continues to operate after exit from Stop Mode. For CSAD = 1 and COP is running on ACLK (COPOSCSEL1 = 1) the following applies: Due to clock domain crossing synchronization there is a latency time of 2 ACLK cycles to enter Stop Mode. After exit from STOP mode (when interrupt service routine is entered) the software has to wait for 2 ACLK cycles before it is allowed to enter Stop mode again (STOP instruction). It is absolutely forbidden to enter Stop Mode before this time of 2 ACLK cycles has elapsed. 0 COP running in Stop Mode (ACLK for COP enabled in Stop Mode). 1 COP stopped in Stop Mode (ACLK for COP disabled in Stop Mode)
4 COP OSCSSEL1	COP Clock Select 1 — COPOSCSEL0 and COPOSCSEL1 combined determine the clock source to the COP (see also Table 9-8). If COPOSCSEL1 = 1, COPOSCSEL0 has no effect regarding clock select and changing the COPOSCSEL0 bit does not re-start the COP time-out period. COPOSCSEL1 selects the clock source to the COP to be either ACLK (derived from trimmable internal RC-Oscillator) or clock selected via COPOSCSEL0 (IRCCLK or OSCCLK). Changing the COPOSCSEL1 bit re-starts the COP time-out period. COPOSCSEL1 can be set independent from value of UPOSC. UPOSC= 0 does not clear the COPOSCSEL1 bit. 0 COP clock source defined by COPOSCSEL0 1 COP clock source is ACLK derived from a trimmable internal RC-Oscillator
3 PRE	RTI Enable During Pseudo Stop Bit — PRE enables the RTI during Pseudo Stop Mode. 0 RTI stops running during Pseudo Stop Mode. 1 RTI continues running during Pseudo Stop Mode if RTIOSCSSEL=1. Note: If PRE=0 or RTIOSCSSEL=0 then the RTI will go static while Stop Mode is active. The RTI counter will <u>not</u> be reset.
2 PCE	COP Enable During Pseudo Stop Bit — PCE enables the COP during Pseudo Stop Mode. 0 COP stops running during Pseudo Stop Mode 1 COP continues running during Pseudo Stop Mode if COPOSCSEL=1 Note: If PCE=0 or COPOSCSEL=0 then the COP will go static while Stop Mode is active. The COP counter will <u>not</u> be reset.

10.3 Key Features

- Programmer's Model with List Based Architecture for conversion command and result value organization
- Selectable resolution of 8-bit, 10-bit, or 12-bit
- Channel select control for n external analog input channels
- Provides up to eight device internal channels (please see the device reference manual for connectivity information and [Figure 10-2](#))
- Programmable sample time
- A sample buffer amplifier for channel sampling (improved performance in view to influence of channel input path resistance versus conversion accuracy)
- Left/right justified result data
- Individual selectable VRH_0/1 and VRL_0/1 inputs (ADC12B_LBA V1 and V2) or VRH_0/1/2 inputs (ADC12B_LBA V3) on a conversion command basis (please see [Figure 10-2](#), [Table 10-2](#))
- Special conversions for selected VRH_0/1 (V1 and V2) or VRH_0/1/2 (V3), VRL_0/1 (V1 and V2) or VRL_0 (V3), $(VRL_0/1 + VRH_0/1) / 2$ (V1 and V2) or $(VRL_0 + VRH_0/1/2) / 2$ (V3) (please see [Table 10-2](#))
- 15 conversion interrupts with flexible interrupt organization per conversion result
- One dedicated interrupt for "End Of List" type commands
- Command Sequence List (CSL) with a maximum number of 64 command entries
- Provides conversion sequence abort
- Restart from top of active Command Sequence List (CSL)
- The Command Sequence List and Result Value List are implemented in double buffered manner (two lists in parallel for each function)
- Conversion Command (CSL) loading possible from System RAM or NVM
- Single conversion flow control register with software selectable access path
- Two conversion flow control modes optimized to different application use cases
- Four option bits in the conversion command for top level SoC specific feature/function implementation option (Please refer to the device reference manual for details of the top level feature/function if implemented)

10.6.3.3 ADC List Usage and Conversion/Conversion Sequence Flow Description

It is the user's responsibility to make sure that the different lists do not overlap or exceed the system RAM area respectively the CSL does not exceed the NVM area if located in the NVM. The error flag IA_EIF will be set for accesses done outside the system RAM area and will cause an error interrupt if enabled for lists that are located in the system RAM.

Generic flow for ADC register load at conversion sequence start/restart:

- It is mandatory that the ADC is idle (no ongoing conversion or conversion sequence).
- It is mandatory to have at least one CSL with valid entries. See also [Section 10.9.7.2, “Restart CSL execution with currently active CSL](#) or [Section 10.9.7.3, “Restart CSL execution with new/other CSL \(alternative CSL becomes active CSL\) — CSL swapping](#) for more details on possible scenarios.
- A Restart Event occurs, which causes the index registers to be cleared (register ADCCIDX and ADCRIDX are cleared) and to point to the top of the corresponding lists (top of active RVL and CSL).
- Load conversion command to background conversion command register 1.
- The control bit(s) RSTA (and LDOK if set) are cleared.
- Wait for Trigger Event to start conversion.

Generic flow for ADC register load during conversion:

- The index registers ADCCIDX is incremented.
- The inactive background command register is loaded with a new conversion command.

Generic flow for ADC result storage at end of conversion:

- Index register ADCRIDX is incremented and the conversion result is stored in system RAM. As soon as the result is successfully stored, any conversion interrupt flags are set accordingly.
- At the conversion boundary the other background command register becomes active and visible in the ADC register map.
- If the last executed conversion command was of type “End Of Sequence”, the ADC waits for the Trigger Event.
- If the last executed conversion command was of type “End Of List” and the ADC is configured in “Restart Mode”, the ADC sets all related flags and stays idle awaiting a Restart Event to continue.
- If the last executed conversion command was of type “End Of List” and the ADC is configured in “Trigger Mode”, the ADC sets all related flags and automatically returns to top of current CSL and is awaiting a Trigger Event to continue.
- If the last executed conversion command was of type “Normal Conversion” the ADC continues command execution in the order of the current CSL (continues conversion).

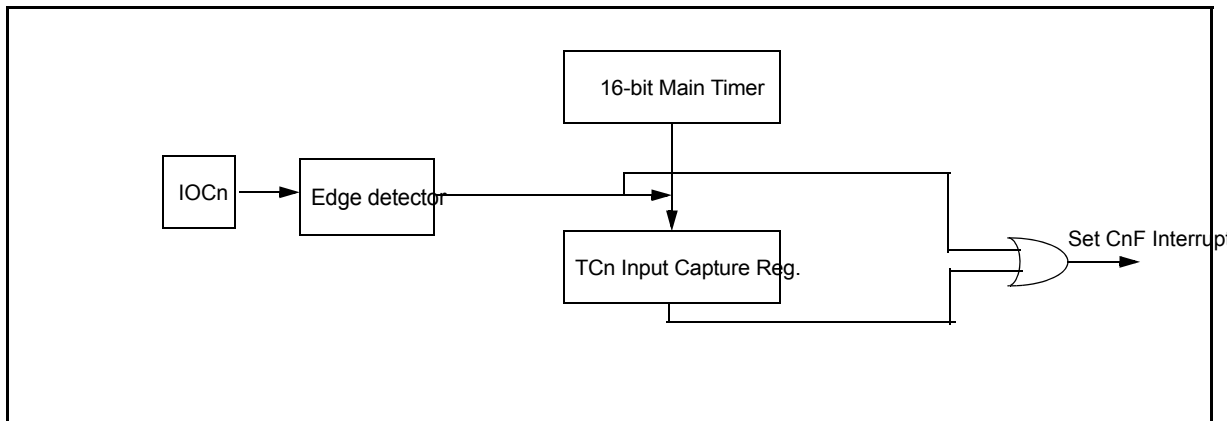


Figure 15-2. Interrupt Flag Setting

15.2 External Signal Description

The TIM16B6CV3 module has a selected number of external pins. Refer to device specification for exact number.

15.2.1 IOC5 - IOC0 — Input Capture and Output Compare Channel 5-0

Those pins serve as input capture or output compare for TIM16B6CV3 channel .

NOTE

For the description of interrupts see [Section 15.6, “Interrupts”](#).

15.3 Memory Map and Register Definition

This section provides a detailed description of all memory and registers.

15.3.1 Module Memory Map

The memory map for the TIM16B6CV3 module is given below in [Figure 15-3](#). The address listed for each register is the address offset. The total address for each register is the sum of the base address for the TIM16B6CV3 module and the address offset for each register.

15.3.2 Register Descriptions

This section consists of register descriptions in address order. Each description includes a standard register diagram with an associated figure number. Details of register bit and field function follow the register diagrams, in bit order.

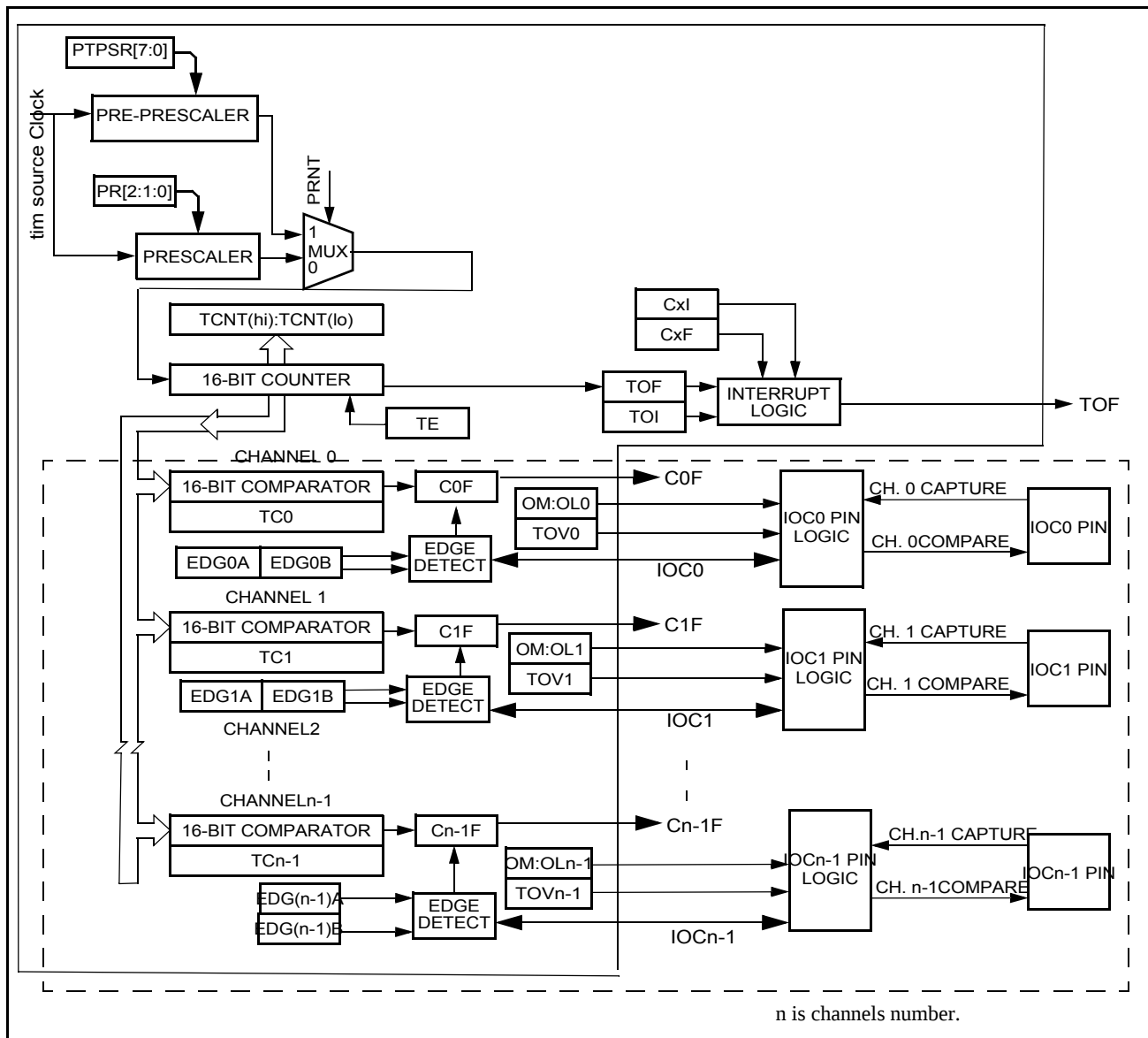


Figure 16-22. Detailed Timer Block Diagram

16.4.1 Prescaler

The prescaler divides the Bus clock by 1, 2, 4, 8, 16, 32, 64 or 128. The prescaler select bits, PR[2:0], select the prescaler divisor. PR[2:0] are in timer system control register 2 (TSCR2).

The prescaler divides the Bus clock by a prescaler value. Prescaler select bits PR[2:0] of in timer system control register 2 (TSCR2) are set to define a prescaler value that generates a divide by 1, 2, 4, 8, 16, 32, 64 and 128 when the PRNT bit in TSCR1 is disabled.

Table 17-10. PWMCTL Field Descriptions

Note: Bits related to available channels have functional significance. Writing to unavailable bits has no effect. Read from unavailable bits return a zero

Field	Description
7 CON67	Concatenate Channels 6 and 7 0 Channels 6 and 7 are separate 8-bit PWMs. 1 Channels 6 and 7 are concatenated to create one 16-bit PWM channel. Channel 6 becomes the high order byte and channel 7 becomes the low order byte. Channel 7 output pin is used as the output for this 16-bit PWM (bit 7 of port PWMP). Channel 7 clock select control-bit determines the clock source, channel 7 polarity bit determines the polarity, channel 7 enable bit enables the output and channel 7 center aligned enable bit determines the output mode.
6 CON45	Concatenate Channels 4 and 5 0 Channels 4 and 5 are separate 8-bit PWMs. 1 Channels 4 and 5 are concatenated to create one 16-bit PWM channel. Channel 4 becomes the high order byte and channel 5 becomes the low order byte. Channel 5 output pin is used as the output for this 16-bit PWM (bit 5 of port PWMP). Channel 5 clock select control-bit determines the clock source, channel 5 polarity bit determines the polarity, channel 5 enable bit enables the output and channel 5 center aligned enable bit determines the output mode.
5 CON23	Concatenate Channels 2 and 3 0 Channels 2 and 3 are separate 8-bit PWMs. 1 Channels 2 and 3 are concatenated to create one 16-bit PWM channel. Channel 2 becomes the high order byte and channel 3 becomes the low order byte. Channel 3 output pin is used as the output for this 16-bit PWM (bit 3 of port PWMP). Channel 3 clock select control-bit determines the clock source, channel 3 polarity bit determines the polarity, channel 3 enable bit enables the output and channel 3 center aligned enable bit determines the output mode.
4 CON01	Concatenate Channels 0 and 1 0 Channels 0 and 1 are separate 8-bit PWMs. 1 Channels 0 and 1 are concatenated to create one 16-bit PWM channel. Channel 0 becomes the high order byte and channel 1 becomes the low order byte. Channel 1 output pin is used as the output for this 16-bit PWM (bit 1 of port PWMP). Channel 1 clock select control-bit determines the clock source, channel 1 polarity bit determines the polarity, channel 1 enable bit enables the output and channel 1 center aligned enable bit determines the output mode.
3 PSWAI	PWM Stops in Wait Mode — Enabling this bit allows for lower power consumption in wait mode by disabling the input clock to the prescaler. 0 Allow the clock to the prescaler to continue while in wait mode. 1 Stop the input clock to the prescaler whenever the MCU is in wait mode.
2 PFRZ	PWM Counters Stop in Freeze Mode — In freeze mode, there is an option to disable the input clock to the prescaler by setting the PFRZ bit in the PWMCTL register. If this bit is set, whenever the MCU is in freeze mode, the input clock to the prescaler is disabled. This feature is useful during emulation as it allows the PWM function to be suspended. In this way, the counters of the PWM can be stopped while in freeze mode so that once normal program flow is continued, the counters are re-enabled to simulate real-time operations. Since the registers can still be accessed in this mode, to re-enable the prescaler clock, either disable the PFRZ bit or exit freeze mode. 0 Allow PWM to continue while in freeze mode. 1 Disable PWM input clock to the prescaler whenever the part is in freeze mode. This is useful for emulation.

17.3.2.7 PWM Clock A/B Select Register (PWMCLKAB)

Each PWM channel has a choice of four clocks to use as the clock source for that channel as described below.

Table 18-3. SCICR1 Field Descriptions (continued)

Field	Description
5 RSRC	Receiver Source Bit — When LOOPS = 1, the RSRC bit determines the source for the receiver shift register input. See Table 18-4. 0 Receiver input internally connected to transmitter output 1 Receiver input connected externally to transmitter
4 M	Data Format Mode Bit — MODE determines whether data characters are eight or nine bits long. 0 One start bit, eight data bits, one stop bit 1 One start bit, nine data bits, one stop bit
3 WAKE	Wakeup Condition Bit — WAKE determines which condition wakes up the SCI: a logic 1 (address mark) in the most significant bit position of a received data character or an idle condition on the RXD pin. 0 Idle line wakeup 1 Address mark wakeup
2 ILT	Idle Line Type Bit — ILT determines when the receiver starts counting logic 1s as idle character bits. The counting begins either after the start bit or after the stop bit. If the count begins after the start bit, then a string of logic 1s preceding the stop bit may cause false recognition of an idle character. Beginning the count after the stop bit avoids false idle character recognition, but requires properly synchronized transmissions. 0 Idle character bit count begins after start bit 1 Idle character bit count begins after stop bit
1 PE	Parity Enable Bit — PE enables the parity function. When enabled, the parity function inserts a parity bit in the most significant bit position. 0 Parity function disabled 1 Parity function enabled
0 PT	Parity Type Bit — PT determines whether the SCI generates and checks for even parity or odd parity. With even parity, an even number of 1s clears the parity bit and an odd number of 1s sets the parity bit. With odd parity, an odd number of 1s clears the parity bit and an even number of 1s sets the parity bit. 0 Even parity 1 Odd parity

Table 18-4. Loop Functions

LOOPS	RSRC	Function
0	x	Normal operation
1	0	Loop mode with transmitter output internally connected to receiver input
1	1	Single-wire mode with TXD pin connected to receiver input

18.3.2.3 SCI Alternative Status Register 1 (SCIASR1)

Module Base + 0x0000

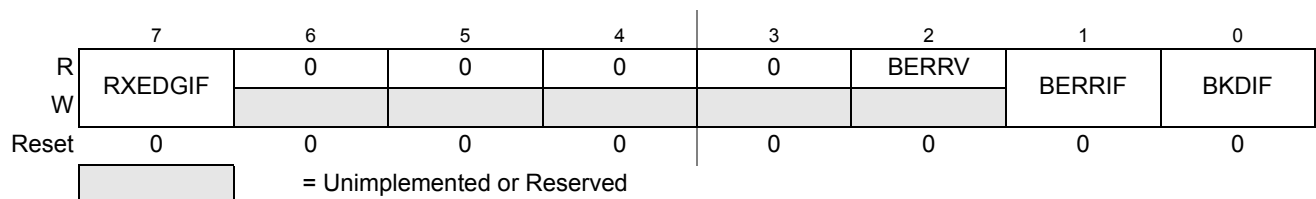


Figure 18-6. SCI Alternative Status Register 1 (SCIASR1)

Read: Anytime, if AMAP = 1

Please note that if the bit time is smaller than the parameter t_{OCLIM} (please refer to electricals), then no overcurrent is reported nor does an overcurrent shutdown occur. However, the current limitation is always engaged in case of a failure.

21.4.3 Modes

Figure 21-11 shows the possible mode transitions depending on control bits, stop mode, and error conditions.

21.4.3.1 Shutdown Mode

The LIN Physical Layer is fully disabled. No wake-up functionality is available. The internal pullup resistor is high ohmic only (330 k Ω) to maintain the LIN Bus pin in the recessive state. LPTxD is not monitored in this mode for a TxD-dominant timeout. All the registers are accessible.

Setting LPE causes the module to leave the shutdown mode and to enter the normal mode or receive only mode (if RXONLY bit is set).

Clearing LPE causes the module to leave the normal or receive only modes and go back to shutdown mode.

21.4.3.2 Normal Mode

The full functionality is available. Both receiver and transmitter are enabled. The internal pullup resistor can be chosen to be high ohmic (330 k Ω) if LPPUE = 0, or LIN compliant (34 k Ω) if LPPUE = 1.

If RXONLY is set, the module leaves normal mode to enter receive only mode.

If the MCU enters stop mode, the LIN Physical Layer enters standby mode.

21.4.3.3 Receive Only Mode

Entering this mode disables the transmitter and immediately stops any on-going transmission. LPTxD is not monitored in this mode for a TxD-dominant timeout.

The receiver is running in full performance mode in all cases.

To return to normal mode, the RXONLY bit must be cleared.

If the device enters stop mode, the module leaves receive only mode to enter standby mode.

21.4.3.4 Standby Mode with Wake-Up Feature

The transmitter of the LIN Physical Layer is disabled and the receiver enters a low power mode.

NOTE

Before entering standby mode, ensure no transmissions are ongoing.

If LPWUE is not set, no wake up feature is available and the standby mode has the same electrical properties as the shutdown mode. This allows a low-power consumption of the device in stop mode if the wake-up feature is not needed.

- Automated program and erase algorithm with verify and generation of ECC parity bits
- Fast sector erase and phrase program operation
- Ability to read the P-Flash memory while programming a word in the EEPROM memory
- Flexible protection scheme to prevent accidental program or erase of P-Flash memory

22.1.2.2 EEPROM Features

- The EEPROM memory is composed of one Flash block divided into sectors of 4 bytes
- Single bit fault correction and double bit fault detection within a word during read operations
- Automated program and erase algorithm with verify and generation of ECC parity bits
- Fast sector erase and word program operation
- Protection scheme to prevent accidental program or erase of EEPROM memory
- Ability to program up to four words in a burst sequence

22.1.2.3 Other Flash Module Features

- No external high-voltage power supply required for Flash memory program and erase operations
- Interrupt generation on Flash command completion and Flash error detection
- Security mechanism to prevent unauthorized access to the Flash memory

22.1.3 Block Diagram

The block diagrams of the Flash modules are shown in the following figures.

22.3.2.9.1 P-Flash Protection Restrictions

In Normal Single Chip mode the general guideline is that P-Flash protection can only be added and not removed. Table 22-22 specifies all valid transitions between P-Flash protection scenarios. Any attempt to write an invalid scenario to the FPROT register will be ignored. The contents of the FPROT register reflect the active protection scenario. See the FPHS and FPLS bit descriptions for additional restrictions.

Table 22-22. P-Flash Protection Scenario Transitions

From Protection Scenario	To Protection Scenario ¹							
	0	1	2	3	4	5	6	7
0	X	X	X	X				
1		X		X				
2			X	X				
3				X				
4				X	X			
5			X	X	X	X		
6		X		X	X		X	
7	X	X	X	X	X	X	X	X

¹ Allowed transitions marked with X, see Figure 22-14 for a definition of the scenarios.

22.3.2.10 EEPROM Protection Register (DFPROT)

The DFPROT register defines which EEPROM sectors are protected against program and erase operations.

Offset Module Base + 0x0009

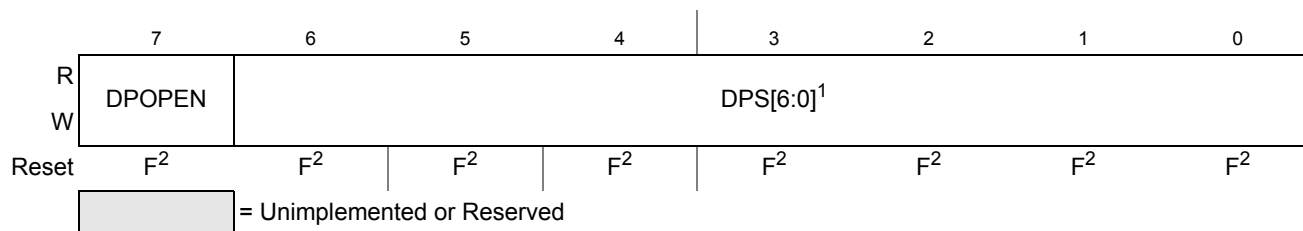


Figure 22-15. EEPROM Protection Register (DFPROT)

¹ The number of implemented DPS bits depends on the EEPROM memory size, as explained below.

² Loaded from Flash configuration field, during reset sequence.

The (unreserved) bits of the DFPROT register are writable in Normal Single Chip mode with the restriction that protection can be added but not removed. Writes in Normal Single Chip mode must increase the DPS value and the DPOPEN bit can only be written from 1 (protection disabled) to 0 (protection enabled). If the DPOPEN bit is set, the state of the DPS bits is irrelevant. All DPOPEN/DPS bit registers are writable without restriction in Special Single Chip Mode.

22.4.7.3 Erase Verify P-Flash Section Command

The Erase Verify P-Flash Section command will verify that a section of code in the P-Flash memory is erased. The Erase Verify P-Flash Section command defines the starting point of the code to be verified and the number of phrases.

Table 22-36. Erase Verify P-Flash Section Command FCCOB Requirements

Register	FCCOB Parameters	
FCCOB0	0x03	Global address [23:16] of a P-Flash block
FCCOB1	Global address [15:0] of the first phrase to be verified	
FCCOB2	Number of phrases to be verified	

Upon clearing CCIF to launch the Erase Verify P-Flash Section command, the Memory Controller will verify the selected section of Flash memory is erased. The CCIF flag will set after the Erase Verify P-Flash Section operation has completed. If the section is not erased, it means blank check failed, both MGSTAT bits will be set.

Table 22-37. Erase Verify P-Flash Section Command Error Handling

Register	Error Bit	Error Condition
FSTAT	ACCERR	Set if CCOBIX[2:0] != 010 at command launch
		Set if command not available in current mode (see Table 22-28)
		Set if an invalid global address [23:0] is supplied see Table 22-2)
		Set if a misaligned phrase address is supplied (global address [2:0] != 000)
		Set if the requested section crosses a the P-Flash address boundary
	FPVIOL	None
	MGSTAT1	Set if any errors have been encountered during the read or if blank check failed.
	MGSTAT0	Set if any non-correctable errors have been encountered during the read or if blank check failed.

22.4.7.4 Read Once Command

The Read Once command provides read access to a reserved 64 byte field (8 phrases) located in the nonvolatile information register of P-Flash. The Read Once field is programmed using the Program Once command described in [Section 22.4.7.6](#). The Read Once command must not be executed from the Flash block containing the Program Once reserved field to avoid code runaway.

Table 22-38. Read Once Command FCCOB Requirements

Register	FCCOB Parameters	
FCCOB0	0x04	Not Required
FCCOB1	Read Once phrase index (0x0000 - 0x0007)	
FCCOB2	Read Once word 0 value	

Table A-17. Run and Wait Current Characteristics for ZVL(A)128/96/64

Conditions are: $V_{SUP} = 18V$, see Table A-14 and Table A-15						
Num	Rating	Symbol	Min	Typ	Max	Unit
1	Run Current, $-40^{\circ}C < T_J \leq 150^{\circ}C$, $f_{bus}=32MHz$	I_{SUPR}	—	21	27	mA
2	Run Current, $150^{\circ}C < T_J < 175^{\circ}C$, $f_{bus}=25MHz$	I_{SUPR}	—	21	27	mA
3	Wait Current, $-40^{\circ}C < T_J \leq 150^{\circ}C$, $f_{bus}=32MHz$	I_{SUPW}	—	13	20	mA
4	Wait Current, $150^{\circ}C < T_J < 175^{\circ}C$, $f_{bus}=25MHz$	I_{SUPW}	—	13	20	mA

Table A-18. Stop Current Characteristics for ZVL(S)32/16/8

Conditions are: $V_{SUP} = 12V$						
Num	Rating ¹	Symbol	Min	Typ	Max	Unit
Stop Current all modules off						
1	$T_J = -40^{\circ}C$	I_{SUPS}	—	20	28	μA
2	$T_J = 25^{\circ}C$	I_{SUPS}	—	23	33	μA
3	$T_J = 85^{\circ}C$	I_{SUPS}	—	44	55	μA
4	$T_J = 105^{\circ}C$	I_{SUPS}	—	63	85	μA
5	$T_J = 125^{\circ}C$	I_{SUPS}	—	115	156	μA
Stop Current API enabled & LINPHY in standby						
6	$T_J = 25^{\circ}C$	I_{SUPS}	—	38	—	μA

¹ If MCU is in STOP long enough then $T_A = T_J$. Die self heating due to stop current can be ignored.

Table A-19. Stop Current Characteristics for ZVL(A)128/96/64

Conditions are: $V_{SUP} = 12V$						
Num	Rating ¹	Symbol	Min	Typ	Max	Unit
Stop Current all modules off						
1	$T_J = -40^{\circ}C$	I_{SUPS}	—	20	40	μA
2	$T_J = 25^{\circ}C$	I_{SUPS}	—	25	50	μA
3	$T_J = 85^{\circ}C$	I_{SUPS}	—	60	107	μA
4	$T_J = 105^{\circ}C$	I_{SUPS}	—	78	176	μA
5	$T_J = 125^{\circ}C$	I_{SUPS}	—	130	301	μA
Stop Current API enabled & LINPHY in standby						
6	$T_J = 25^{\circ}C$	I_{SUPS}	—	53	—	μA

¹ If MCU is in STOP long enough then $T_A = T_J$. Die self heating due to stop current can be ignored.

Table A-20. Pseudo Stop Current Characteristics for ZVL(S)32/16/8

Conditions are: $V_{SUP} = 12V$, API, COP & RTI enabled						
Num	Rating	Symbol	Min	Typ	Max	Unit
1	$T_J = 25^{\circ}C$	I_{SUPPS}	—	155	350	μA

Appendix D

LINPHY Electrical Specifications

D.1 Maximum Ratings

Table D-1. Maximum ratings of the LINPHY

Num	Ratings	Symbol	Value	Unit
1	DC voltage on LIN	V_{LIN}	-32 to +42	V
2	Continuous current on LIN	I_{LIN}	± 200 ¹	mA

¹The current on the LIN pin is internally limited. Therefore, it should not be possible to reach the 200mA anyway.

D.2 Static Electrical Characteristics

Table D-2. Static electrical characteristics of the LINPHY

Characteristics noted under conditions $5.5V \leq V_{LINSUP} \leq 18V$ unless otherwise noted ^{1 2 3} . Typical values noted reflect the approximate parameter mean at $T_A = 25^\circ C$ under nominal conditions unless otherwise noted.						
Num	Ratings	Symbol	Min	Typ	Max	Unit
1	V_{LINSUP} operating range	V_{LINSUP_LIN}	5.5 ^{1 2}	12	18	V
2	Current limitation into the LIN pin in dominant state ⁴ $V_{LIN} = V_{LINSUP_LIN_MAX}$	I_{LIN_LIM}	40		200	mA
3	Input leakage current in dominant state, driver off, internal pull-up on $V_{LIN} = 0V$, $V_{LINSUP} = 12V$	$I_{LIN_PAS_dom}$	-1			mA
4	Input leakage current in recessive state, driver off $5.5V < V_{LINSUP} < 18V$, $5.5V < V_{LIN} < 18V$, $V_{LIN} > V_{LINSUP}$	$I_{LIN_PAS_rec}$			20	μA
5	Input leakage current when ground disconnected $-40^\circ C < T_J < 175^\circ C$ $GND_{Device} = V_{LINSUP}$, $0V < V_{LIN} < 18V$, $V_{LINSUP} = 12V$	$I_{LIN_NO_GND}$	-1		1	mA
6	Input leakage current when battery disconnected $-40^\circ C < T_J < 175^\circ C$ $V_{LINSUP} = GND_{Device}$, $0 < V_{LIN} < 18V$	$I_{LIN_NO_BAT}$			30	μA
7	Receiver dominant state	V_{LINdom}			0.4	V_{LINSUP}
8	Receiver recessive state	V_{LINrec}	0.6			V_{LINSUP}
9	$V_{LIN_CNT} = (V_{th_dom} + V_{th_rec})/2$	V_{LIN_CNT}	0.475	0.5	0.525	V_{LINSUP}
10	$V_{HYS} = V_{th_rec} - V_{th_dom}$	V_{HYS}			0.175	V_{LINSUP}
11	Maximum capacitance allowed on slave node including external components	C_{slave}		220	250	pF
12a	Capacitance of the LIN pin, Recessive state	C_{LIN}		20		pF

The data retention and program/erase cycling failure rates are specified at the operating conditions noted. The program/erase cycle count on the sector is incremented every time a sector or mass erase event is executed.

NOTE

All values shown in [Table E-3](#) are preliminary and subject to further characterization.

Table E-3. NVM Reliability Characteristics

NUM	Rating	Symbol	Min	Typ	Max	Unit
Program Flash Arrays						
1	Data retention at an average junction temperature of $T_{Javg} = 85^{\circ}\text{C}$ ¹ after up to 10,000 program/erase cycles	t_{NVMRET}	20	100^2	—	Years
2	Program Flash number of program/erase cycles ($-40^{\circ}\text{C} \leq t_j \leq 150^{\circ}\text{C}$)	n_{FLPE}	10K	100K^3	—	Cycles
EEPROM Array						
3	Data retention at an average junction temperature of $T_{Javg} = 85^{\circ}\text{C}$ ¹ after up to 100,000 program/erase cycles	t_{NVMRET}	5	100^2	—	Years
4	Data retention at an average junction temperature of $T_{Javg} = 85^{\circ}\text{C}$ ¹ after up to 10,000 program/erase cycles	t_{NVMRET}	10	100^2	—	Years
5	Data retention at an average junction temperature of $T_{Javg} = 85^{\circ}\text{C}$ ¹ after less than 100 program/erase cycles	t_{NVMRET}	20	100^2	—	Years
6	EEPROM number of program/erase cycles ($-40^{\circ}\text{C} \leq t_j \leq 150^{\circ}\text{C}$)	n_{FLPE}	100K	500K^3	—	Cycles

¹ T_{Javg} does not exceed 85°C in a typical temperature profile over the lifetime of a consumer, industrial or automotive application.

² Typical data retention values are based on intrinsic capability of the technology measured at high temperature and de-rated to 25°C using the Arrhenius equation. For additional information on how NXP defines Typical Data Retention, please refer to Engineering Bulletin EB618

³ Spec table quotes typical endurance evaluated at 25°C for this product family. For additional information on how NXP defines Typical Endurance, please refer to Engineering Bulletin EB619.